# Adaptive Execution on 3D Microprocessors

Koji Inoue Kyushu University

### Outline

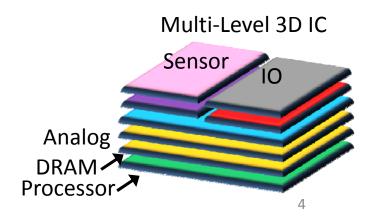
- Why 3D?
- Will 3D always work well?
- Support Adaptive Execution!
  - Memory Hierarchy Run-time Optimization
- Conclusions

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## From 2D to 3D! (not only TV)

- Stack Multiple Dies
- Connect Dies with Through Silicon Vias



# Chip Implementation Examples from ISSCC'09

- Image Sensors
- SRAM for SoCs
- DRAM
- Multi-core + SRAM connected with wireless TSVs

U. Kang et al., "8Gb DDR3 DRAM Using Through-Silicon-Via Technology," ISSCC'09.

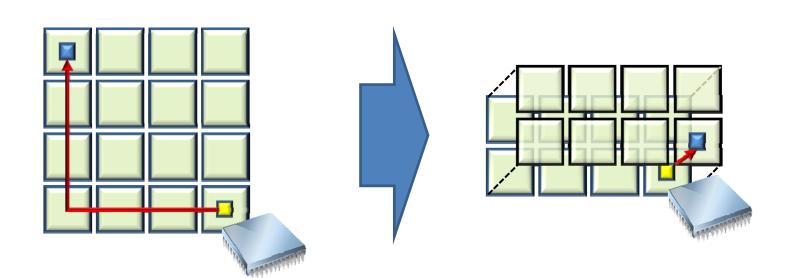
H. Saito et al., "A Chip-Stacked Memory for On-Chip SRAM-Rich SoCs and Processors, " ISSCC'09.

V. Suntharalingam et al., "A 4-Side Tileable Back Illuminated 3D-Integrated Mpixel CMOS Image Sensor," ISSCC'09.

K. Niitsu et al., "An Inductive-Coupling Link for 3D Integration of a 90nm CMOS Processor and a 65nm CMOS SRAM," ISSCC'09.

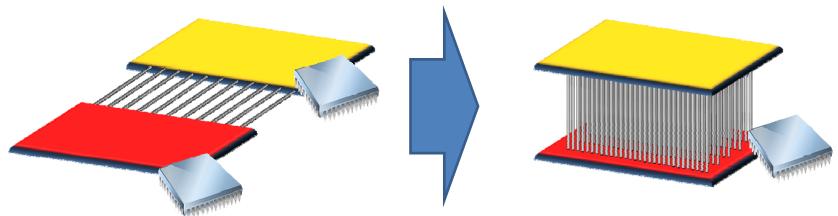
# Why 3D? (1/2)

- Wire Length Reduction
  - Replace long, high capacitance wires by TSVs
  - Low Latency, Low Energy
- Small footprint



# Why 3D?(2/2)

- Integration
  - From "Off-Chip" to "On-Chip"
  - Improved Communication
    - Low Latency, High Bandwidth, and Low Energy
  - Heterogeneous Integration
    - E.g. Emerging Devices



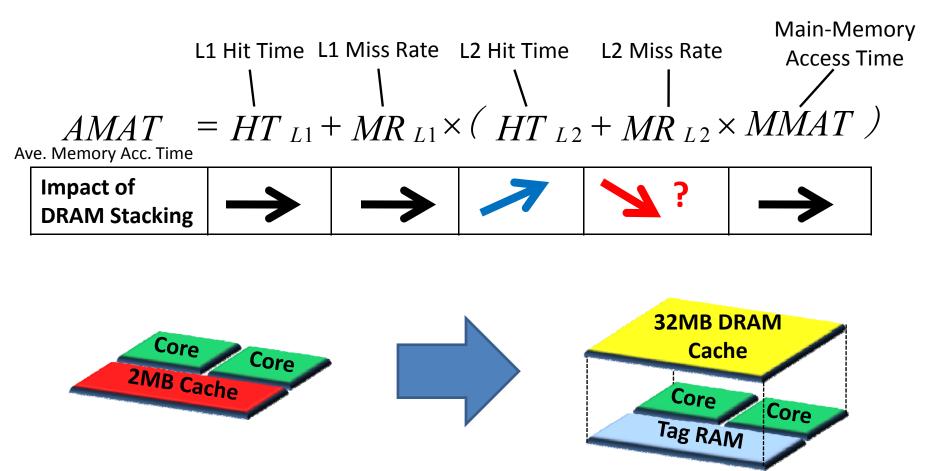
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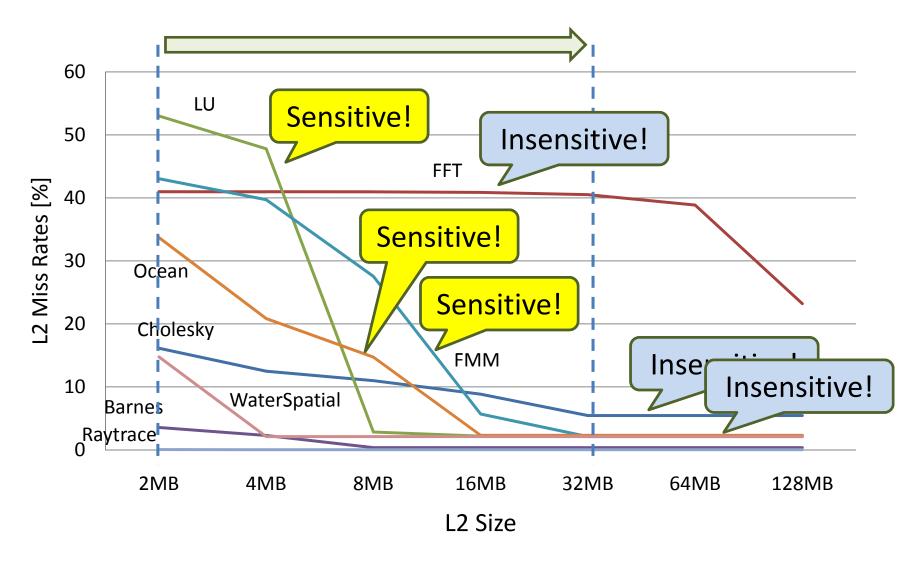
## Importance of On-Chip Caches

- Memory-Wall Problem
  - Memory bandwidth does not scale with the # of cores
  - Growing speed gap between processor cores and DRAMs
  - So, Becomes more serious
- Let's increase on-chip cache capacity, but...
  - Requires large chip area

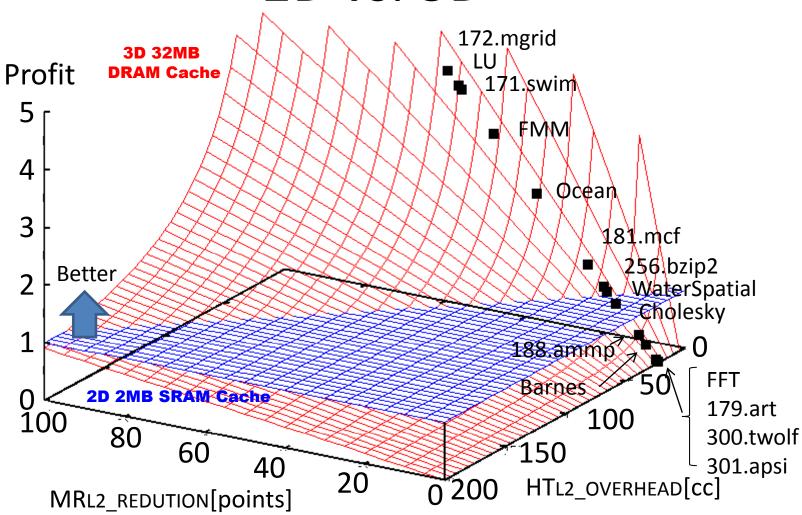
# Will 3D always work well? "Stacking a DRAM Cache"



### Cache-Size Sensitivity Varies among Programs!

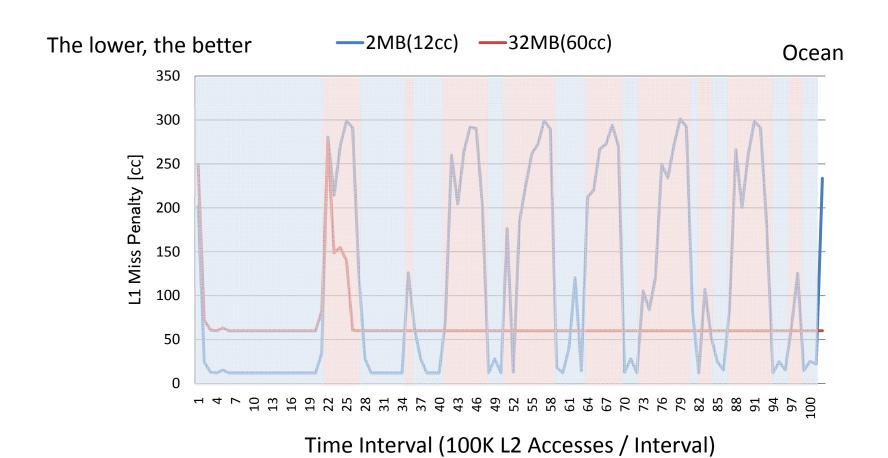


### 2D vs. 3D



$$Profit = \frac{MR_{L2\_REDUCTION} \times MMAT}{HT_{L2\_OVERHEAD}}$$

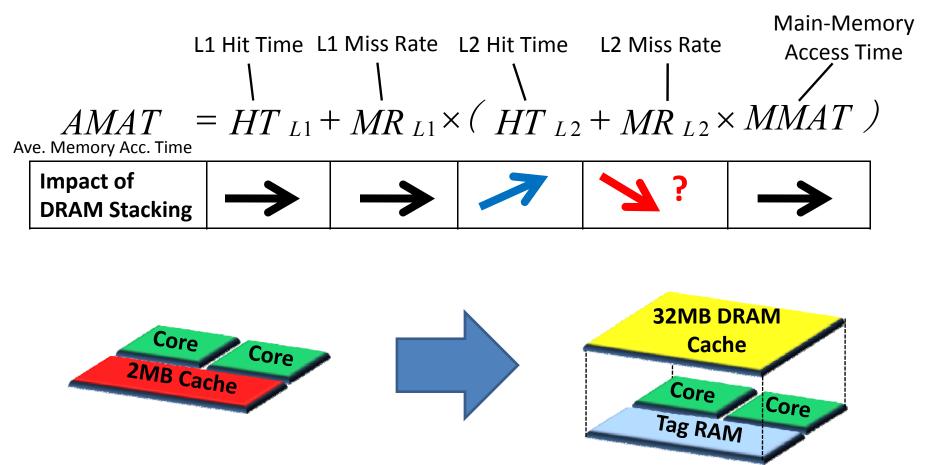
### Appropriate Cache Size Varies within Programs!



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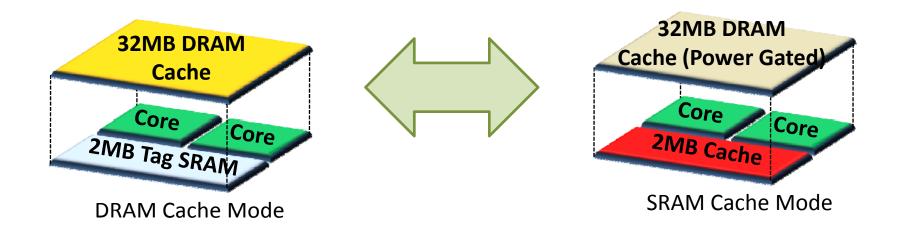
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# Will 3D always work well? "Stacking a DRAM Cache"

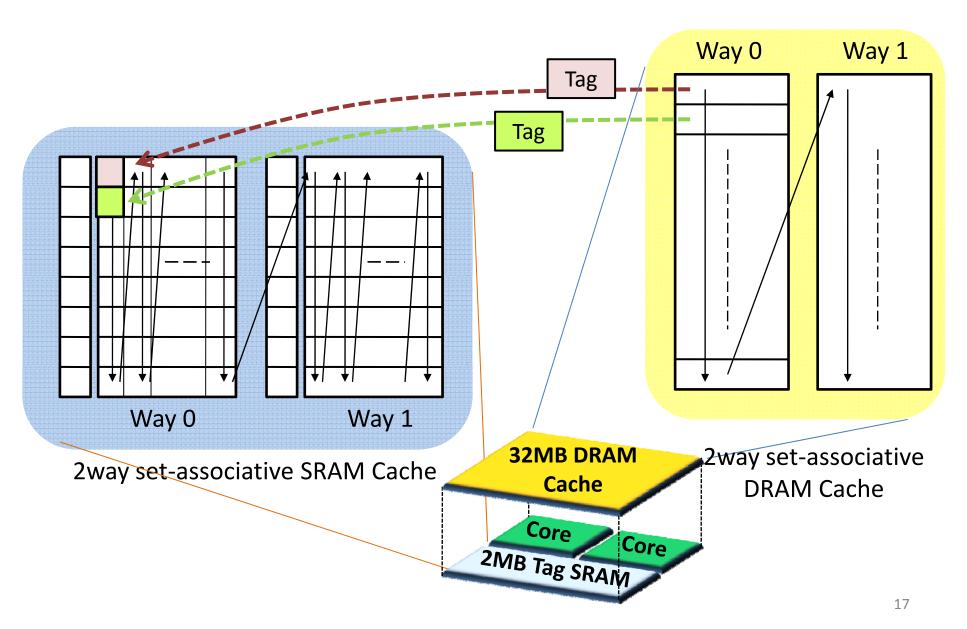


### SRAM/DRAM Hybrid Cache Architecture

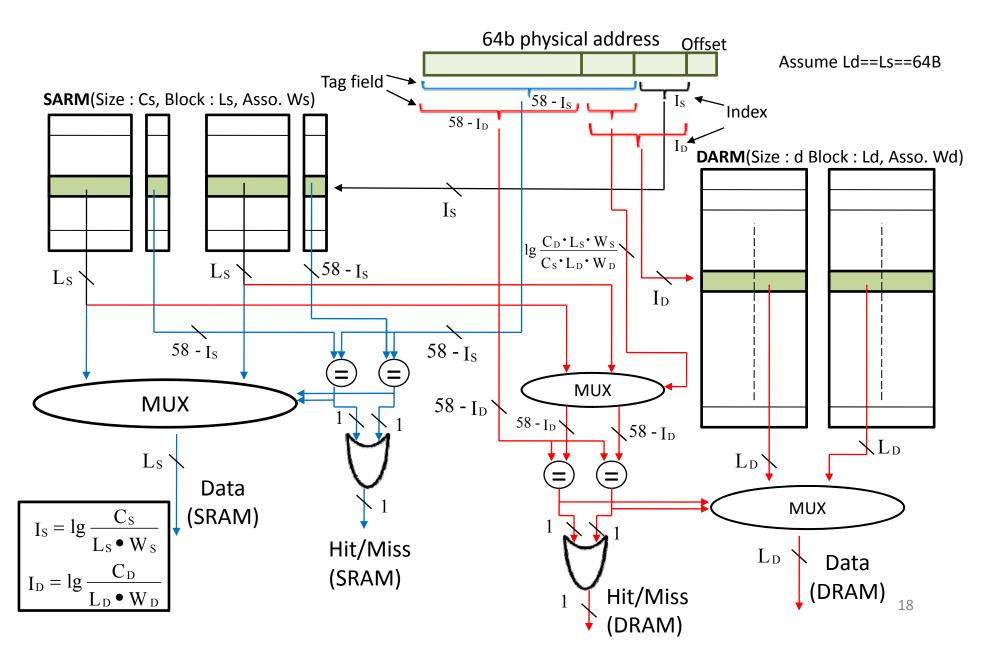
- Support Two Operation Modes
  - High-Speed, Small Cache Mode (or SRAM Cache Mode)
  - Low-Speed, Large Cache Mode (or DRAM Cache Mode)
- Adapt to variation of application behavior



# Microarchitecture (1/2)



# Microarchitecture (2/2)

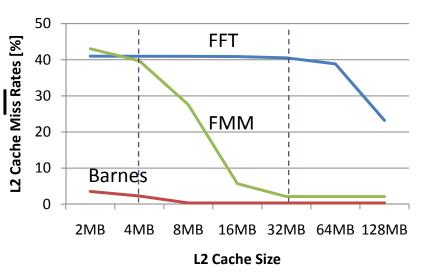


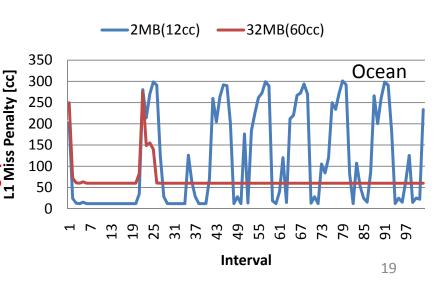
## How to Adapt

- Static Approach
- Static Approach

  Optimizes at program level

  Does not change it during execution
  - Needs a static analysis
- Dynamic Approach
  - Optimizes at interval level (or phase level)
     Needs a run-time profiling

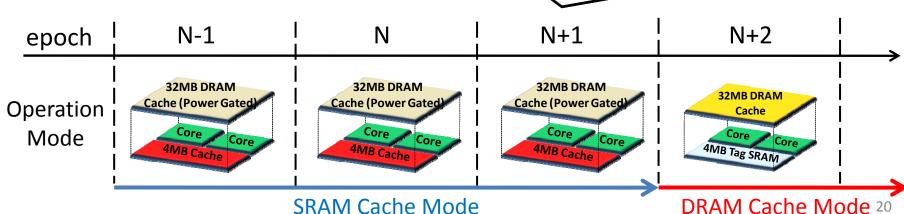




### Run-Time Mode Selection

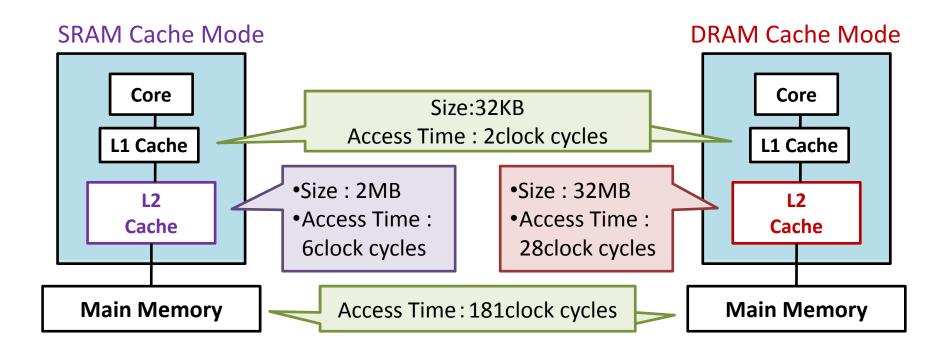
- Divide Program Execution into "epochs", e.g. 200K L2 Misses
- Predict an Appropriate Operation Mode for Next Epoch
- On SRAM mode, a small tag RAM which stores sampled tags is used to predict DRAM mode miss rates

 $if \ MR_{L2SRAM} - MR_{L2DRAM} > \frac{HT_{L2DRAM} - HT_{L2SRAM} + AveOverhead}{MMAT}$  then transit from SRAM mode to DRAM mode!

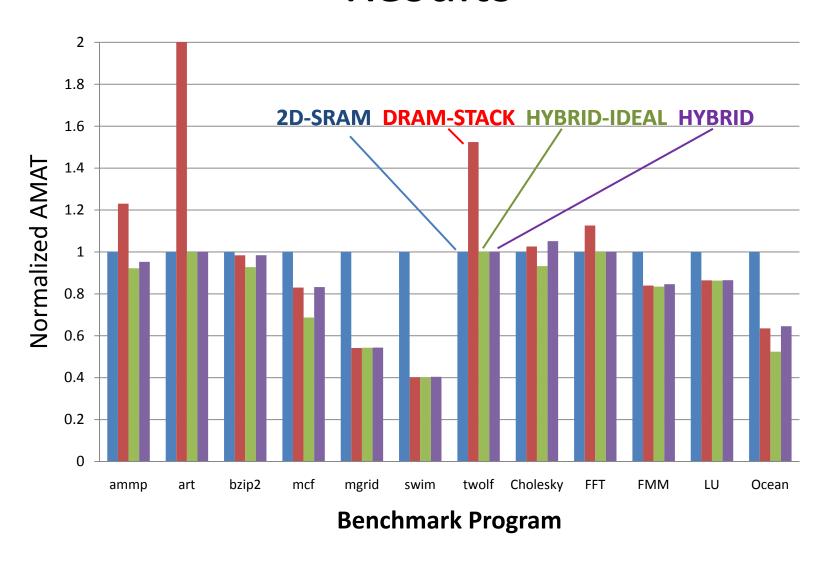


## **Experimental Set Up**

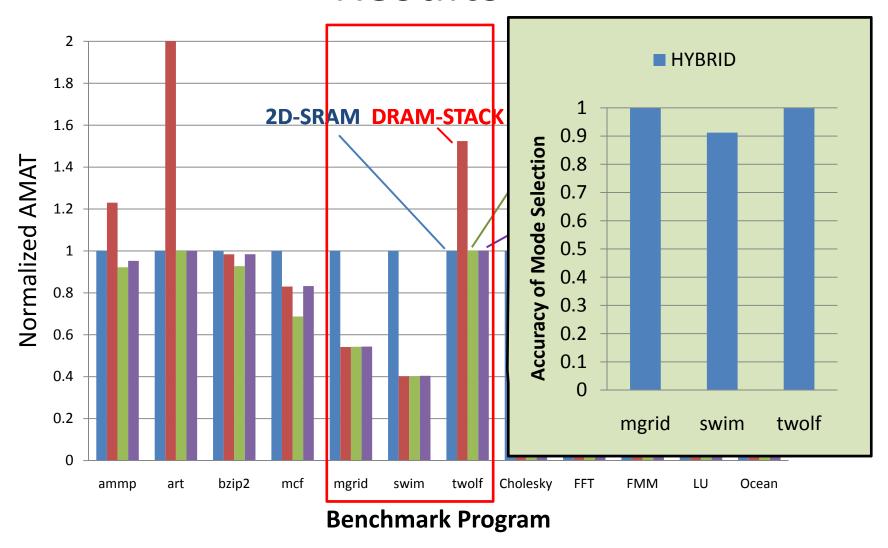
- Processor: In-Order
- Benchmarks: SPEC CPU 2000, Splash2



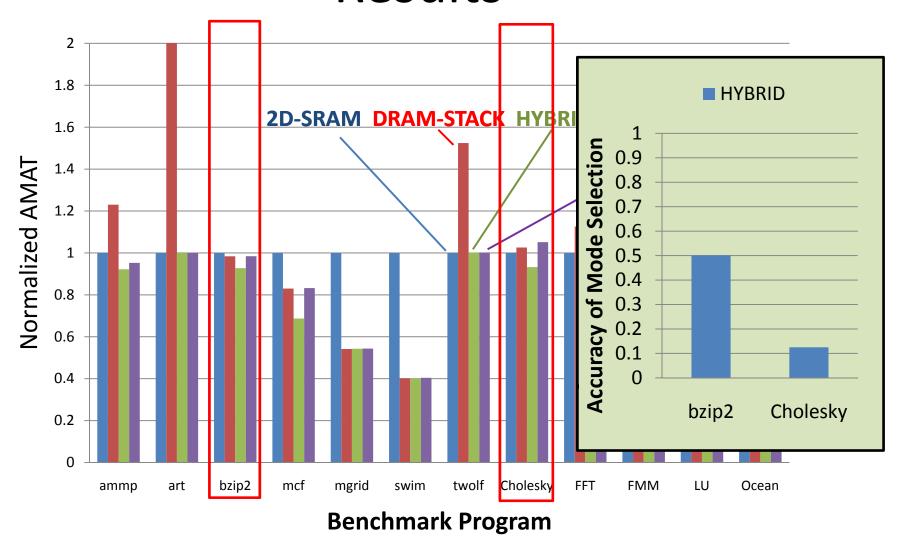
## Results



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#### Conclusions

- The 3D solution is one of the most promising ways to achieve...
  - High performance
  - Low energy
- It does not ALWAYS work well!
- Run-time adaptive execution by considering memory access behavior

## Acknowledgement

 This research was supported in part by New Energy and Industrial Technology Development Organization